



XPED COMPLETES PORTING TO CHIPSET MANUFACTURERS

Highlights

- Xped progresses key MOU's signed in 2016
- ADRC porting completed under the terms of the MOU's with two major chipset manufacturers
- Porting of ADRC nearing completion on Telink 8269 SOC
- Introductions to large OEM and specialised gateway manufacturers have now progressed to licensing negotiations

Xped Limited (ASX: XPE) ("Xped" or "the Company") wishes to announce it has successfully ported ADRC technologies to chipsets from both US Listed chipset manufacturers previously announced in separate Memorandums of Understanding ("MOU") signed this year and is close to finishing a port to the Telink 8269 SOC which is expected to be completed by the end of 2016.

Following on from progressing the MOU's, the Company is now formally seeking approval to release the suppressed identity of each chipset manufacturer.

All chipset manufacturers have been very supportive of the Company in its quest to port ADRC firmware onto their respective chipsets and products, with each providing access to latest silicon and engineering resources. The next step in our engagement is to co-market the ADRC integrated solution to their respective customer base.



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Xped is also excited to confirm it is nearing completion of the porting of ADRC to Telink's 8269 SOC. In a further development the Company is now working with Telink to incorporate their patented BLE mesh capabilities within ADRC with this work expected to be completed in the Q1 2017 time frame.

One of the benefits of working with these leading chipset manufacturers, is the ability to offer ADRC on a range of chipsets for a number of customer and partner applications which are well suited to many vertical market segments. While we still have several months of activity engaging with our partners end-customers, this approach will allow us to scale our ADRC technology with more efficiency.

Following the successful porting of ADRC, the Company is now in discussions with clients of the chipset manufacturers, with the aim of reaching licensing agreements.

Xped has seen a high level of interest from all direct introductions made from the chipset manufacturers to date.

Commenting on these latest developments Martin Despain said: "Xped's ADRC technology was introduced to me as revolutionary, and this is why I decided to join the Company to lead them on their global quest. The market opportunity for an end to end platform utilising Xped's ADRC and RML language is unique, and offers significant value added opportunities for OEM companies and brands seeking to add a platform and software solution to hardware devices. Following expansion of engineering resources and focus on business development we are already in licensing negotiations, which we hope to formalise before the end of this calendar year. It is important to note that booking of revenue from licensing would typically take 6-9 months due to manufacturing changes and implementations by those licensing our technology".

Further updates on licensing negotiations will occur as they progress to formal signing.

The Company will also be planning a joint media release with each undisclosed MOU party once formal permission is granted to Xped.

Martin Despain Managing Director





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ABOUT XPED

Xped has developed revolutionary and patent protected technology that allows any consumer, regardless of their technical capability, to connect, monitor and control devices and appliances found in our everyday environment. It's as simple as two people shaking hands. By enabling the Internet of Things, Xped's ADRC platform will bring benefit to Manufacturers, Retailers, Service Providers and Consumers.

At Xped, we're Making Technology Easy Again



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